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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

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Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	20
Program Memory Size	3KB (2K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	72 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc57ct-04-so

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

### 5.0 RESET

PIC16C5X devices may be RESET in one of the following ways:

- Power-On Reset (POR)
- MCLR Reset (normal operation)
- MCLR Wake-up Reset (from SLEEP)
- WDT Reset (normal operation)
- WDT Wake-up Reset (from SLEEP)

Table 5-1 shows these RESET conditions for the PCL and STATUS registers.

Some registers are not affected in any RESET condition. Their status is unknown on POR and unchanged in any other RESET. Most other registers are reset to a "RESET state" on Power-On Reset (POR), MCLR or WDT Reset. A MCLR or WDT wake-up from SLEEP also results in a device RESET, and not a continuation of operation before SLEEP. The  $\overline{\text{TO}}$  and  $\overline{\text{PD}}$  bits (STATUS <4:3>) are set or cleared depending on the different RESET conditions (Table 5-1). These bits may be used to determine the nature of the RESET.

Table 5-3 lists a full description of RESET states of all registers. Figure 5-1 shows a simplified block diagram of the On-chip Reset circuit.

#### TABLE 5-1: STATUS BITS AND THEIR SIGNIFICANCE

Condition	то	PD
Power-On Reset	1	1
MCLR Reset (normal operation)	u	u
MCLR Wake-up (from SLEEP)	1	0
WDT Reset (normal operation)	0	1
WDT Wake-up (from SLEEP)	0	0

Legend: u = unchanged, x = unknown, - = unimplemented read as '0'.

#### TABLE 5-2: SUMMARY OF REGISTERS ASSOCIATED WITH RESET

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	<u>Value</u> on MCLR and WDT Reset
03h	STATUS	PA2	PA1	PA0	TO	PD	Z	DC	С	0001 1xxx	000q quuu

Legend: u = unchanged, x = unknown, q = see Table 5-1 for possible values.

#### TABLE 5-3: RESET CONDITIONS FOR ALL REGISTERS

Register	Address	Power-On Reset	MCLR or WDT Reset
W	N/A	xxxx xxxx	uuuu uuuu
TRIS	N/A	1111 1111	1111 1111
OPTION	N/A	11 1111	11 1111
INDF	00h	xxxx xxxx	uuuu uuuu
TMR0	01h	XXXX XXXX	uuuu uuuu
PCL	02h	1111 1111	1111 1111
STATUS	03h	0001 1xxx	000q quuu
FSR <sup>(1)</sup>	04h	1xxx xxxx	luuu uuuu
PORTA	05h	xxxx	uuuu
PORTB	06h	XXXX XXXX	uuuu uuuu
PORTC <sup>(2)</sup>	07h	XXXX XXXX	uuuu uuuu
General Purpose Register Files	07-7Fh	xxxx xxxx	սսսս սսսս

Legend: x = unknown u = unchanged - = unimplemented, read as '0'<math>q = see tables in Table 5-1 for possible values.

- Note 1: These values are valid for PIC16C57/CR57/CR58/CR58. For the PIC16C54/CR54/C55/C56/CR56, the value on RESET is 111x xxxx and for MCLR and WDT Reset, the value is 111u uuuu.
  - **2:** General purpose register file on PIC16C54/CR54/C56/CR56/C58/CR58.

#### FIGURE 5-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



#### 5.1 Power-On Reset (POR)

The PIC16C5X family incorporates on-chip Power-On Reset (POR) circuitry which provides an internal chip RESET for most power-up situations. To use this feature, the user merely ties the MCLR/VPP pin to VDD. A simplified block diagram of the on-chip Power-On Reset circuit is shown in Figure 5-1.

The Power-On Reset circuit and the Device Reset Timer (Section 5.2) circuit are closely related. On power-up, the RESET latch is set and the DRT is <u>RESET</u>. The DRT timer begins counting once it detects MCLR to be high. After the time-out period, which is typically 18 ms, it will RESET the reset latch and thus end the on-chip RESET signal.

A power-up example where MCLR is not tied to VDD is shown in Figure 5-3. VDD is allowed to rise and stabilize before bringing MCLR high. The chip will actually come out of reset TDRT msec after MCLR goes high.

In Figure 5-4, the on-chip Power-On Reset feature is being used (MCLR and VDD are tied together). The VDD is stable before the start-up timer times out and there is no problem in getting a proper RESET. However, Figure 5-5 depicts a problem situation where VDD rises too slowly. The time between when the DRT senses a high on the MCLR/VPP pin, and when the MCLR/VPP pin (and VDD) actually reach their full value, is too long. In this situation, when the start-up timer times out, VDD has not reached the VDD (min) value and the chip is, therefore, not guaranteed to function correctly. For such situations, we recommend that external RC circuits be used to achieve longer POR delay times (Figure 5-2).

Note: When the device starts normal operation (exits the RESET condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in RESET until the operating conditions are met.

For more information on PIC16C5X POR, see *Power-Up Considerations* - AN522 in the <u>Embedded Control Handbook</u>.

The POR circuit does not produce an internal RESET when VDD declines.

#### FIGURE 5-2:

#### EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



- External Power-On Reset circuit is required only if VDD power-up is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.
- R < 40 kΩ is recommended to make sure that voltage drop across R does not violate the device electrical specification.
- R1 =  $100\Omega$  to 1 k $\Omega$  will limit any current flowing into  $\overline{MCLR}$  from external capacitor C in the event of  $\overline{MCLR}$  pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

### 12.0 ELECTRICAL CHARACTERISTICS - PIC16C54A

#### Absolute Maximum Ratings<sup>(†)</sup>

Ambient Temperature under bias	–55°C to +125°C
Storage Temperature	65°C to +150°C
Voltage on VDD with respect to VSS	0V to +7.5V
Voltage on MCLR with respect to Vss <sup>(1)</sup>	0V to +14V
Voltage on all other pins with respect to Vss	0.6V to (VDD + 0.6V)
Total power dissipation <sup>(2)</sup>	800 mW
Max. current out of Vss pin	150 mA
Max. current into VDD pin	100 mA
Max. current into an input pin (T0CKI only)	±500 μA
Input clamp current, Iik (VI < 0 or VI > VDD)	±20 mA
Output clamp current, IOK (VO < 0 or VO > VDD)	±20 mA
Max. output current sunk by any I/O pin	
Max. output current sourced by any I/O pin	
Max. output current sourced by a single I/O port (PORTA, B or C)	40 mA
Max. output current sunk by a single I/O port (PORTA, B or C)	50 mA

- **Note 1:** Voltage spikes below Vss at the  $\overline{\text{MCLR}}$  pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50 to 100  $\Omega$  should be used when applying a "low" level to the  $\overline{\text{MCLR}}$  pin rather than pulling this pin directly to Vss.
  - **2:** Power Dissipation is calculated as follows: Pdis = VDD x {IDD  $-\Sigma$  IOH} +  $\Sigma$  {(VDD VOH) x IOH} +  $\Sigma$ (VOL x IOL)

† NOTICE: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

#### 12.2 DC Characteristics: PIC16C54/55/56/57-RCI, XTI, 10I, HSI, LPI (Industrial)

PIC16C54/55/56/57-RCI, XTI, 10I, HSI, LPI (Industrial)				Standard Operating Conditions (unless otherwise specified) Operating Temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial						
Param No.	Symbol	Characteristic/Device	Min	Тур†	Max	Units	Conditions			
D001	Vdd	Supply Voltage PIC16C5X-RCI PIC16C5X-XTI PIC16C5X-10I PIC16C5X-HSI PIC16C5X-HSI	3.0 3.0 4.5 4.5		6.25 6.25 5.5 5.5 6.25	V V V V				
D002	Vdr	RAM Data Retention Voltage <sup>(1)</sup>	2.5	1.5*		V	Device in SLEEP mode			
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset			
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset			
D010	IDD	Supply Current <sup>(2)</sup> PIC16C5X-RCI <sup>(3)</sup> PIC16C5X-XTI PIC16C5X-10I PIC16C5X-HSI PIC16C5X-HSI PIC16C5X-LPI		1.8 1.8 4.8 9.0 15	3.3 3.3 10 10 20 40	mA mA mA mA μA	Fosc = 4 MHz, VDD = $5.5V$ Fosc = 4 MHz, VDD = $5.5V$ Fosc = 10 MHz, VDD = $5.5V$ Fosc = 10 MHz, VDD = $5.5V$ Fosc = 20 MHz, VDD = $5.5V$ Fosc = $32$ kHz, VDD = $3.0V$ , WDT disabled			
D020	IPD	Power-down Current <sup>(2)</sup>	_	4.0 0.6	14 12	μΑ μΑ	VDD = 3.0V, WDT enabled VDD = 3.0V, WDT disabled			

\* These parameters are characterized but not tested.

- † Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.
- Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
  - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
    - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.
    - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
  - **3:** Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

AC Chara	cteristics	$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \\ -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for extended} \end{array}$								
Param No.	Symbol	Characteristic	Characteristic Min Typ† Max Units Condition							
1	Tosc	External CLKIN Period <sup>(1)</sup>	250			ns	XT OSC mode			
			100		—	ns	10 MHz mode			
			50		—	ns	HS OSC mode (Comm/Ind)			
			62.5		—	ns	HS OSC mode (Ext)			
			25		—	μS	LP OSC mode			
		Oscillator Period <sup>(1)</sup>	250	—	—	ns	RC OSC mode			
			250		10,000	ns	XT OSC mode			
			100		250	ns	10 MHz mode			
			50		250	ns	HS OSC mode (Comm/Ind)			
			62.5		250	ns	HS OSC mode (Ext)			
			25		—	μS	LP OSC mode			
2	Тсу	Instruction Cycle Time <sup>(2)</sup>	—	4/Fosc	—	—				
3	TosL,	Clock in (OSC1) Low or High	85*	—	—	ns	XT oscillator			
	TosH	Time	20*	—	—	ns	HS oscillator			
			2.0*		—	μS	LP oscillator			
4	TosR,	Clock in (OSC1) Rise or Fall	—	_	25*	ns	XT oscillator			
	TosF	Time	—	—	25*	ns	HS oscillator			
			—	—	50*	ns	LP oscillator			

#### TABLE 12-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C54/55/56/57

\* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

**Note 1:** All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (TCY) equals four times the input oscillator time base period.

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#### 13.4 DC Characteristics: PIC16CR54A-04E, 10E, 20E (Extended)

DC CH	ARACTE	RISTICS	Standard Operating Conditions (unless otherwise specified)Operating Temperature $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended							
Param No.	Symbol	Characteristic	Min	Тур†	Мах	Units	Conditions			
D030	VIL	Input Low Voltage I/O ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1	Vss Vss Vss Vss Vss		0.15 VDD 0.15 VDD 0.15 VDD 0.15 VDD 0.15 VDD 0.3 VDD	V V V V	Pin at hi-impedance RC mode only <sup>(3)</sup> XT, HS and LP modes			
D040	Vih	Input High Voltage I/O ports I/O ports I/O ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1	0.45 VDD 2.0 0.36 VDD 0.85 VDD 0.85 VDD 0.85 VDD 0.85 VDD 0.7 VDD		VDD VDD VDD VDD VDD VDD VDD VDD	V V V V V V V	For all VDD <sup>(4)</sup> 4.0V < VDD ≤ 5.5V <sup>(4)</sup> VDD > 5.5V RC mode only <sup>(3)</sup> XT, HS and LP modes			
D050	VHYS	Hysteresis of Schmitt Trigger inputs	0.15 Vdd*	—	—	V				
D060	lı∟	Input Leakage Current <sup>(1,2)</sup> I/O ports MCLR MCLR T0CKI OSC1	-1.0 -5.0  -3.0 -3.0	0.5 — 0.5 0.5 0.5	+1.0 	μΑ μΑ μΑ μΑ	For VDD $\leq$ 5.5V: VSS $\leq$ VPIN $\leq$ VDD, pin at hi-impedance VPIN = VSS + 0.25V VPIN = VDD VSS $\leq$ VPIN $\leq$ VDD VSS $\leq$ VPIN $\leq$ VDD, XT, HS and LP modes			
D080	Vol	Output Low Voltage I/O ports OSC2/CLKOUT		_	0.6 0.6	V V	IOL = 8.7 mA, VDD = 4.5V IOL = 1.6 mA, VDD = 4.5V, RC mode only			
D090	Vон	Output High Voltage <sup>(2)</sup> I/O ports OSC2/CLKOUT	VDD - 0.7 VDD - 0.7			V V	IOH = $-5.4$ mA, VDD = $4.5$ V IOH = $-1.0$ mA, VDD = $4.5$ V, RC mode only			

These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

**2:** Negative current is defined as coming out of the pin.

3: For the RC mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

4: The user may use the better of the two specifications.

#### FIGURE 13-5: TIMER0 CLOCK TIMINGS - PIC16CR54A



#### TABLE 13-4: TIMER0 CLOCK REQUIREMENTS - PIC16CR54A

	Standard Operating Conditions (unless otherwise specified)											
	AC Char	actorictics	Operating Temperat	Dperating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial								
			-40°C ≤	$TA \le +8$	B5°C f	or indus	strial					
	$-40^{\circ}C \le TA \le +125^{\circ}C$ for extended											
Param No.	Symbol		Characteristic	Min	Тур†	Max	Units	Conditions				
40	Tt0H	T0CKI High	Pulse Width									
			- No Prescaler	0.5 TCY + 20*	—	—	ns					
			- With Prescaler	10*		—	ns					
41	Tt0L	T0CKI Low	Pulse Width									
			- No Prescaler	0.5 TCY + 20*	—	—	ns					
			- With Prescaler	10*	_	—	ns					
42	Tt0P	T0CKI Peric	od	20 or <u>Tcy + 40</u> *		—	ns	Whichever is greater.				
				N				N = Prescale Value				
								(1, 2, 4,, 256)				

These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

#### 15.1 DC Characteristics: PIC16C54A-04, 10, 20 (Commercial) PIC16C54A-04I, 10I, 20I (Industrial) PIC16LC54A-04 (Commercial) PIC16LC54A-04I (Industrial)

PIC16L0 PIC16L0 (Comm	C54A-04 C54A-04I nercial, Ind	lustrial)	$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \end{array}$							
PIC16C PIC16C (Comm	54A-04, 1( 54A-04I, 1 nercial, Ind	<b>0, 20</b> <b>0I, 20I</b> Iustrial)	<b>Stand</b> Opera	$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}\mbox{C} \leq T\mbox{A} \leq +70^{\circ}\mbox{C for commercial} \\ -40^{\circ}\mbox{C} \leq T\mbox{A} \leq +85^{\circ}\mbox{C for industrial} \end{array}$						
Param No.	Symbol	Characteristic/Device	Min	Тур†	Max	Units	Conditions			
	Vdd	Supply Voltage								
D001		PIC16LC54A	3.0 2.5	_	6.25 6.25	V V	XT and RC modes LP mode			
D001A		PIC16C54A	3.0 4.5	_	6.25 5.5	V V	RC, XT and LP modes HS mode			
D002	Vdr	RAM Data Retention Voltage <sup>(1)</sup>	—	1.5*	—	V	Device in SLEEP mode			
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset			
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	—	-	V/ms	See Section 5.1 for details on Power-on Reset			
	IDD	Supply Current <sup>(2)</sup>								
D005		PIC16LC5X	_	0.5	2.5	mA	Fosc = 4.0 MHz, VDD = 5.5V, RC <sup>(3)</sup> and XT modes			
				11	27	μΑ	Fosc = 32 kHz, VDD = 2.5V, WDT disabled, LP mode, Commercial			
			_	11	35	μΑ	Fosc = 32 kHz, VDD = 2.5V, WDT disabled, LP mode, Industrial			
D005A		PIC16C5X	—	1.8	2.4	mA	Fosc = 4.0 MHz, VDD = 5.5V, RC <sup>(3)</sup> and XT modes			
			—	2.4	8.0	mA	FOSC = 10 MHz, VDD = 5.5V, HS mode			
			—	4.5	16	mA	FOSC = 20  MHz,  VDD = 5.5V, HS mode			
				14	29	μA	HOSC = 32 kHz, VDD = 3.0V,			
			-	17	37	μΑ	Fosc = 32 kHz, VDD = 3.0V, WDT disabled, LP mode, Industrial			

Legend: Rows with standard voltage device data only are shaded for improved readability.

These parameters are characterized but not tested.

- † Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.
- **Note 1:** This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
  - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
    - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, T0CKI = VDD, MCLR = VDD; WDT enabled/ disabled as specified.
    - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
  - 3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in k $\Omega$ .

#### 15.1 DC Characteristics: PIC16C54A-04, 10, 20 (Commercial) PIC16C54A-04I, 10I, 20I (Industrial) PIC16LC54A-04 (Commercial) PIC16LC54A-04I (Industrial)

PIC16LC54A-04       Standard Operating Conditions (unless otherwise spee         PIC16LC54A-04I       Operating Temperature       0°C ≤ TA ≤ +70°C for commercial, Industrial)         (Commercial, Industrial)       -40°C ≤ TA ≤ +85°C for industrial							tions (unless otherwise specified) $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial $40^{\circ}C \le TA \le +85^{\circ}C$ for industrial		
PIC16C54A-04, 10, 20 PIC16C54A-04I, 10I, 20I (Commercial, Industrial)				$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \end{array}$					
Param No.	Symbol	Characteristic/Device	Min Typ† Max Units Conditions						
	IPD	Power-down Current <sup>(2)</sup>							
D006		PIC16LC5X	—	2.5	12	μΑ	VDD = 2.5V, WDT enabled, Commercial		
			—	0.25	4.0	μΑ	VDD = 2.5V, WDT disabled, Commercial		
			$-$ 2.5 14 $\mu$ A VDD = 2.5V, WDT enabled, industrial $-$ 0.25 5.0 $\mu$ A VDD = 2.5V, WDT disabled, Industrial						
D006A		PIC16C5X	_	4.0	12	μΑ	VDD = 3.0V, WDT enabled, Commercial		
			—	0.25	4.0	μA	VDD = 3.0V, WDT disabled, Commercial		
			—	5.0	14	μΑ	VDD = 3.0V, WDT enabled, Industrial		
				0.3	5.0	μA	$v \Box U = 3.0v, v U T uisabled, industrial$		

Legend: Rows with standard voltage device data only are shaded for improved readability.

\* These parameters are characterized but not tested.

† Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

**Note 1:** This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

- a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, T0CKI = VDD, MCLR = VDD; WDT enabled/ disabled as specified.
- b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
- 3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in k $\Omega$ .

#### 15.2 DC Characteristics: PIC16C54A-04E, 10E, 20E (Extended) PIC16LC54A-04E (Extended)

PIC16I	C54A-04F	•	Stand	, ard One	ratino	, Condi	tions (unless otherwise specified)			
(Exten	ded)	-	Operating Temperature $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended							
PIC16C (Exten	<b>54A-04E,</b> ded)	10E, 20E	Standard Operating Conditions (unless otherwise specified Operating Temperature $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended							
Param No.	Symbol	Characteristic	Min	Тур†	Мах	Units	Conditions			
	Vdd	Supply Voltage								
D001		PIC16LC54A	3.0 2.5		6.25 6.25	V V	XT and RC modes LP mode			
D001A		PIC16C54A	3.5 4.5		5.5 5.5	V V	RC and XT modes HS mode			
D002	Vdr	RAM Data Retention Voltage <sup>(1)</sup>		1.5*	—	V	Device in SLEEP mode			
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	-	Vss	_	V	See Section 5.1 for details on Power-on Reset			
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	_	—	V/ms	See Section 5.1 for details on Power-on Reset			
	IDD	Supply Current <sup>(2)</sup>								
D010		PIC16LC54A	-	0.5	25	mA	Fosc = 4.0 MHz, VDD = 5.5V, RC <sup>(3)</sup> and XT modes			
			-	11	27	μA	Fosc = 32 kHz, VDD = 2.5V, LP mode, Commercial			
				11	35	μA	Fosc = 32 kHz, VDD = 2.5V, LP mode, Industrial			
			—	11	37	μA	Fosc = 32 kHz, VDD = 2.5V, LP mode, Extended			
D010A		PIC16C54A	—	1.8	3.3	mA	Fosc = 4.0 MHz, VDD = 5.5V, RC <sup>(3)</sup> and XT modes			
			-	4.8	10	mA	Fosc = 10 MHz, VDD = 5.5V, HS mode			
			-	9.0	20	mA	Fosc = 20 MHz, VDD = 5.5V, HS mode			

Legend: Rows with standard voltage device data only are shaded for improved readability.

- \* These parameters are characterized but not tested.
- † Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.
- Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
  - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
    - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, TOCKI = VDD, MCLR = VDD; WDT enabled/ disabled as specified.
    - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
  - **3:** Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

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#### FIGURE 16-5: TYPICAL IPD vs. VDD, WATCHDOG DISABLED (25°C)







NOTES:

### 17.0 ELECTRICAL CHARACTERISTICS - PIC16LC54A

#### Absolute Maximum Ratings<sup>(†)</sup>

Ambient temperature under bias	–55°C to +125°C
Storage temperature	–65°C to +150°C
Voltage on VDD with respect to VSS	0 to +7.5V
Voltage on MCLR with respect to Vss	0 to +14V
Voltage on all other pins with respect to Vss	–0.6V to (VDD + 0.6V)
Total power dissipation <sup>(1)</sup>	
Max. current out of Vss pin	150 mA
Max. current into Vod pin	100 mA
Max. current into an input pin (T0CKI only)	±500 μA
Input clamp current, Iк (Vi  < 0 or Vi  > VDD)	±20 mA
Output clamp current, Iок (Vo < 0 or Vo > Voo)	±20 mA
Max. output current sunk by any I/O pin	
Max. output current sourced by any I/O pin	20 mA
Max. output current sourced by a single I/O (Port A, B or C)	50 mA
Max. output current sunk by a single I/O (Port A, B or C)	50 mA
<b>Note 1:</b> Power dissipation is calculated as follows: Pdis = VDD x {IDD - $\sum$ IOH} + $\sum$ {(VD	D-VOH) X IOH} + $\Sigma$ (VOL X IOL)

**†** NOTICE: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

#### TABLE 17-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C5X, PIC16CR5X

AC Chara	cteristics	$ \begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \\ -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for extended} \\ \end{array} $					
Param No.	Symbol	Characteristic	Min	Тур†	Мах	Units	Conditions
2	Тсу	Instruction Cycle Time <sup>(2)</sup>	—	4/Fosc			
3	TosL, TosH	Clock in (OSC1) Low or High	50*		_	ns	XT oscillator
		Time	20*	—	_	ns	HS oscillator
			2.0*	—	_	μS	LP oscillator
4	TosR, TosF	Clock in (OSC1) Rise or Fall	-		25*	ns	XT oscillator
		Time	—	—	25*	ns	HS oscillator
			—	_	50*	ns	LP oscillator

- \* These parameters are characterized but not tested.
- † Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- **Note 1:** All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.

When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (TCY) equals four times the input oscillator time base period.









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## FIGURE 18-10: VTH (INPUT THRESHOLD TRIP POINT VOLTAGE) OF OSC1 INPUT (IN XT, HS AND LP MODES) vs. VDD









#### FIGURE 18-17: PORTA, B AND C IOL vs. Vol, VDD = 3 V





#### FIGURE 19-5: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16C5X-40

#### TABLE 19-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16C5X-40

AC Charac	teristics	Standard Operating Conditions (unless otherwise specified)Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ (commercial)Operating Voltage VDD range is described in Section 19.1.					
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	1000*		_	ns	VDD = 5.0V
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	9.0*	18*	30*	ms	VDD = 5.0V (Comm)
32	Tdrt	Device Reset Timer Period	9.0*	18*	30*	ms	VDD = 5.0V (Comm)
34	Tioz	I/O Hi-impedance from MCLR Low	100*	300*	1000*	ns	

\* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested. NOTES: